MBRD320, MBRD340 and MBRD360 are Preferred Devices

SWITCHMODE Power Rectifiers

DPAK Surface Mount Package

These state-of-the-art devices are designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

Features

- Extremely Fast Switching
- Extremely Low Forward Drop
- Platinum Barrier with Avalanche Guardrings
- Pb-Free Packages are Available

Mechanical Characteristics:

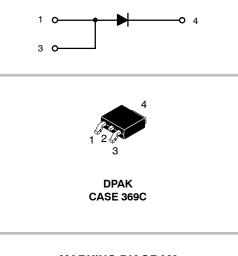
- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes; 260°C Max. for 10 Seconds



ON Semiconductor®

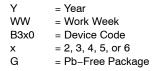
http://onsemi.com

SCHOTTKY BARRIER RECTIFIERS 3.0 AMPERES, 20 – 60 VOLTS



MARKING DIAGRAM





ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS

Rating Symbol	0 milest	MBRD					1114
	320	330	340	350	360	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
Average Rectified Forward Current ($T_C = +125^{\circ}C$, Rated V_R)	I _{F(AV)}	3			А		
Peak Repetitive Forward Current, T _C = +125°C (Rated V _R , Square Wave, 20 kHz)	I _{FRM}	6			A		
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	75			A		
Peak Repetitive Reverse Surge Current (2 μs, 1 kHz)	I _{RRM}	1		А			
Operating Junction Temperature Range (Note 1)	TJ	-65 to +175		°C			
Storage Temperature Range	T _{stg}	-65 to +175		°C			
Voltage Rate of Change (Rated V _R)	dv/dt	10,000		V/μs			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6	°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Note 2)	R_{\thetaJA}	80	°C/W

ELECTRICAL CHARACTERISTICS

	VF	0.6 0.45 0.7 0.625	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25^{\circ}C$) (Rated dc Voltage, $T_C = +125^{\circ}C$)	İR	0.2 20	mA

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

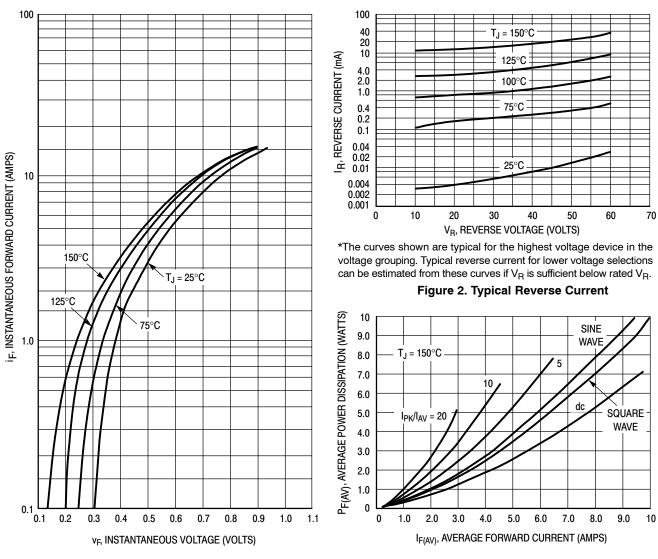
2. Rating applies when surface mounted on the minimum pad size recommended.

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Package	Shipping [†]	
DPAK	75 Units / Rail	
DPAK (Pb-Free)	75 Units / Rail	
DPAK	1800 Tape & Reel	
DPAK (Pb-Free)	1800 Tape & Reel	
DPAK	2500 Tape & Reel	
DPAK (Pb-Free)	2500 Tape & Reel	
DPAK	75 Units / Rail	
DPAK (Pb-Free)	75 Units / Rail	
DPAK	1800 Tape & Reel	
DPAK (Pb-Free)	1800 Tape & Reel	
DPAK	2500 Tape & Reel	
DPAK (Pb-Free)	2500 Tape & Reel	
DPAK	75 Units / Rail	
DPAK (Pb-Free)	75 Units / Rail	
DPAK	1800 Tape & Reel	
DPAK (Pb-Free)	1800 Tape & Reel	
DPAK	2500 Tape & Reel	
DPAK (Pb-Free)	2500 Tape & Reel	
DPAK	75 Units / Rail	
DPAK (Pb-Free)	75 Units / Rail	
DPAK	1800 Tape & Reel	
DPAK (Pb-Free)	1800 Tape & Reel	
DPAK	2500 Tape & Reel	
DPAK (Pb-Free)	2500 Tape & Reel	
DPAK	75 Units / Rail	
DPAK (Pb-Free)	75 Units / Rail	
DPAK	1800 Tape & Reel	
DPAK (Pb-Free)	1800 Tape & Reel	
DPAK	2500 Tape & Reel	
DPAK (Pb-Free)	2500 Tape & Reel	
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+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



TYPICAL CHARACTERISTICS

Figure 1. Typical Forward Voltage

Figure 3. Average Power Dissipation

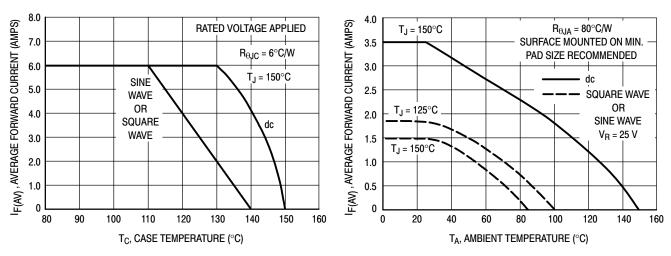




Figure 5. Current Derating, Ambient

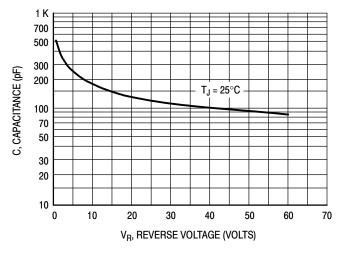
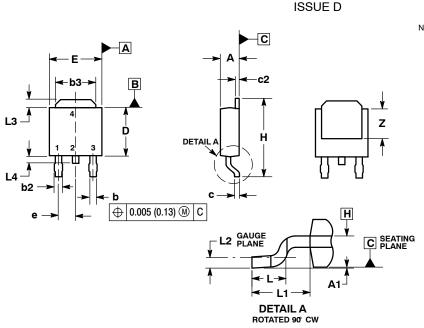


Figure 6. Typical Capacitance

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C-01

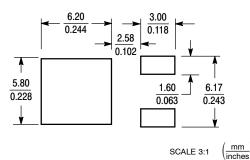


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN
- DIMENSIONS b3, L3 and Z. DIMENSIONS D AND E DO NOT INCLUDE MOLD 4 FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY. 6. DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020	BSC	0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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